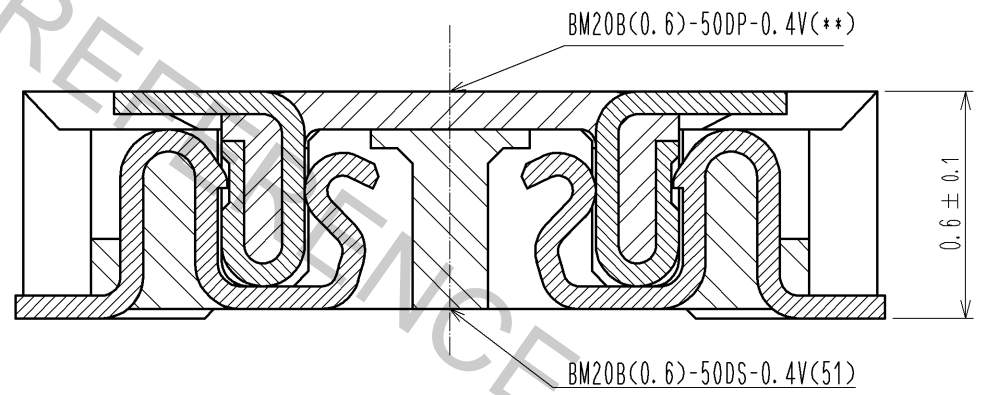


ENGAGEMENT FIGURE (50:1)

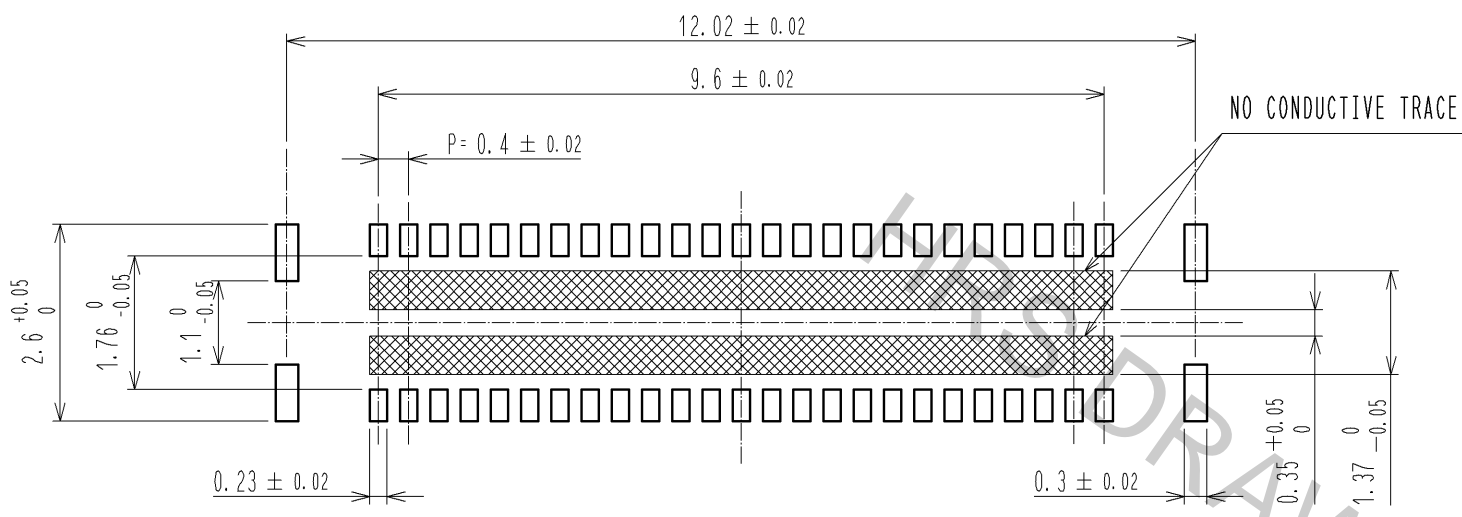


- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
- 2 CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μm MIN
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 3 METAL FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

| NO. | MATERIAL | FINISH | REMARKS | NO. | MATERIAL | FINISH | REMARKS |
|-----|-----------------|--------|-------------------------------|-----|-----------|--------|------------------------------|
| 4 | PS | | CLEAR (EMBOSSED CARRIER TAPE) | | | | |
| 3 | BRASS | 3 | | 7 | PS | | CLEAR (REINFORCEMENT COLLAR) |
| 2 | PHOSPHOR BRONZE | 2 | | 6 | PS | | BLACK (PLASTIC REEL) |
| 1 | LCP | | UL94 V-0, BLACK | 5 | POLYESTER | | CLEAR (COVER TAPE) |

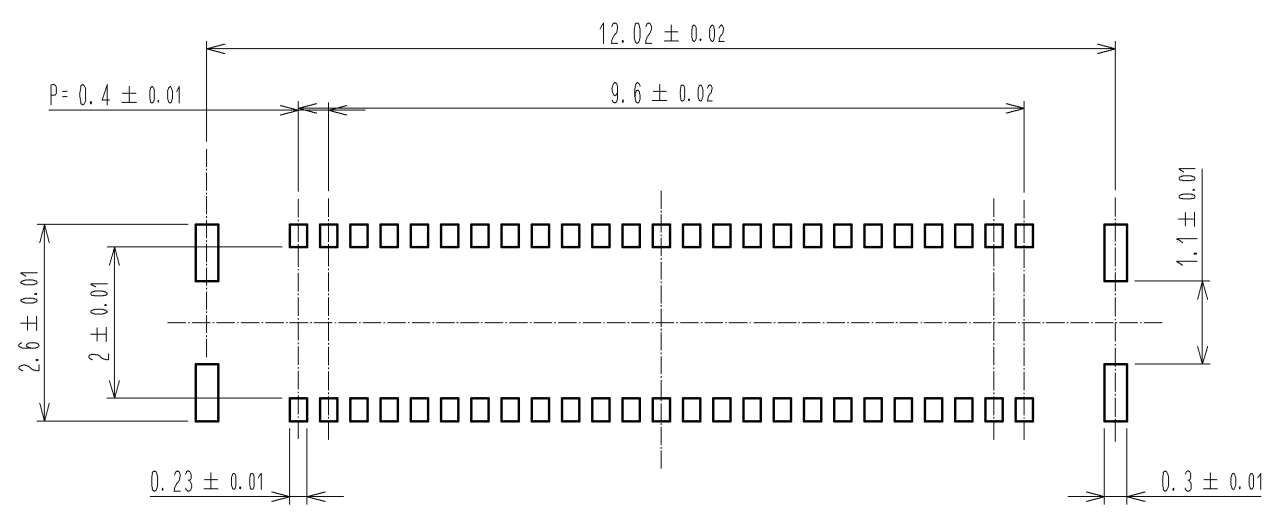
| UNITS | SCALE | COUNT | DESCRIPTION OF REVISIONS | DESIGNED | CHECKED | DATE |
|------------------------|-------|-------|--------------------------|-----------------------------------|---------|------|
| mm | 10:1 | △ | | | | |
| APPROVED : KH. IKEDA | | | 13.08.07 | DRAWING NO. EDC3-347101-01 | | |
| CHECKED : TS. MIYAZAKI | | | 13.08.07 | PART NO. BM20B(0.6)-50DS-0.4V(51) | | |
| DESIGNED : RT. SHIMIZU | | | 13.08.07 | CODE NO. CL684-9314-0-51 | | |
| DRAWN : KR. AJITO | | | 13.08.07 | 1/3 | | |

◆ RECOMMENDED PCB LAYOUT

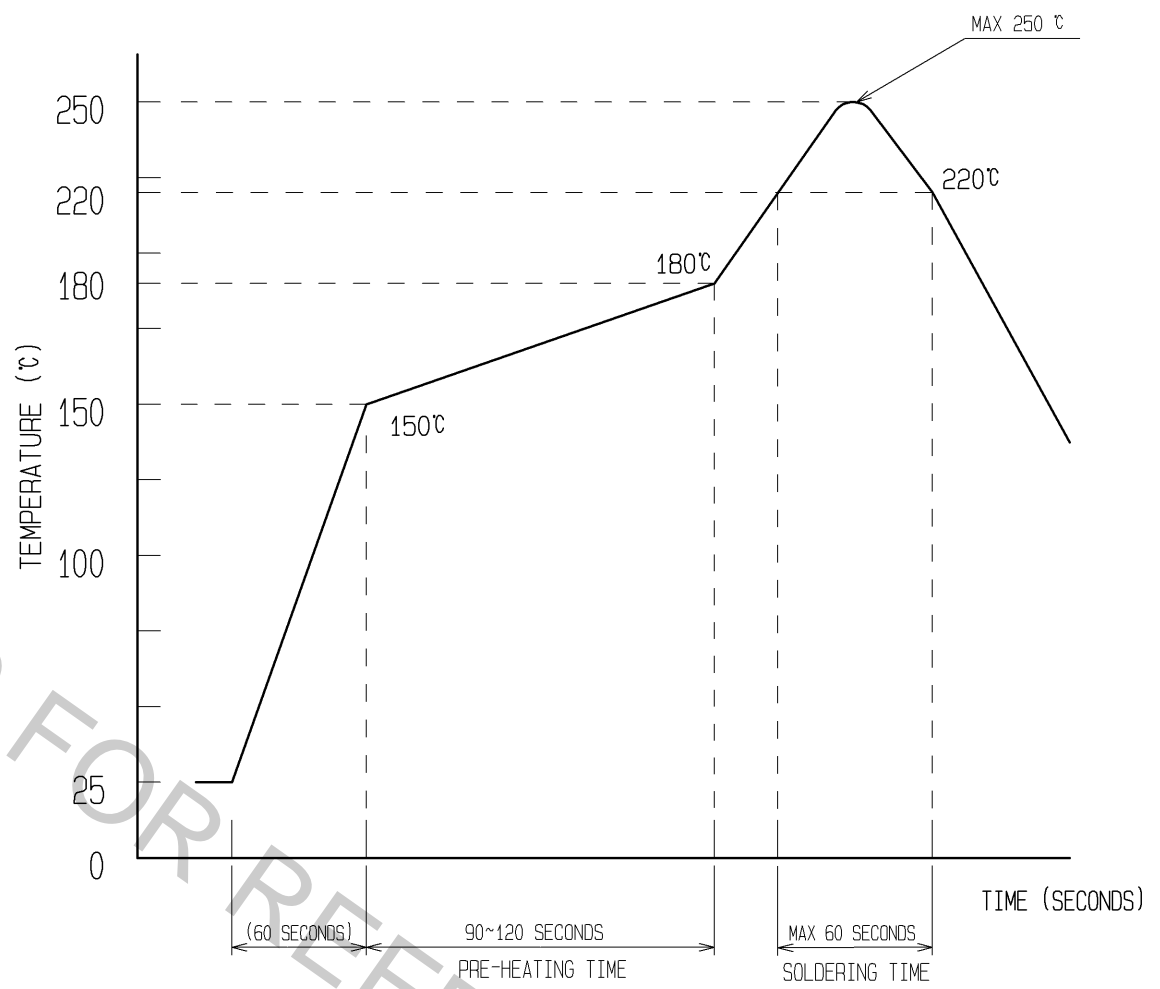


◆ RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : 100 μm



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

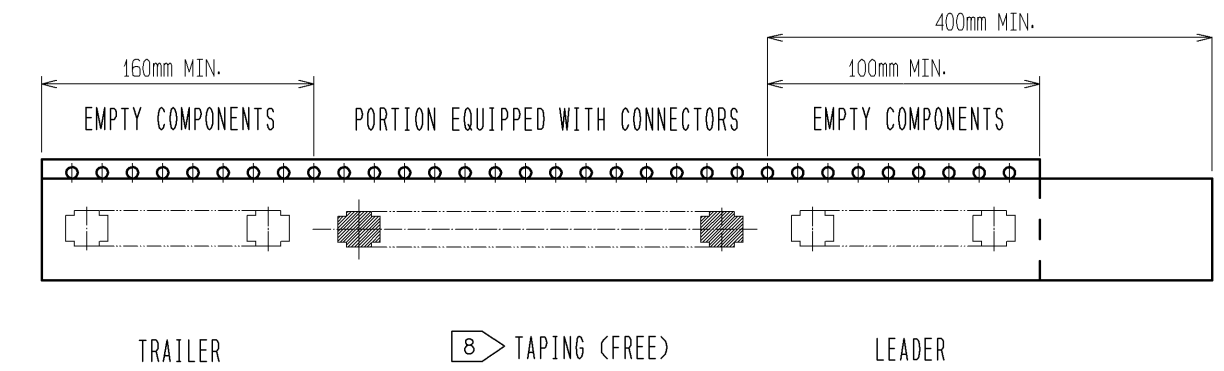
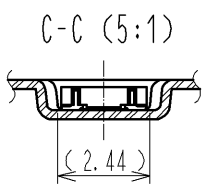
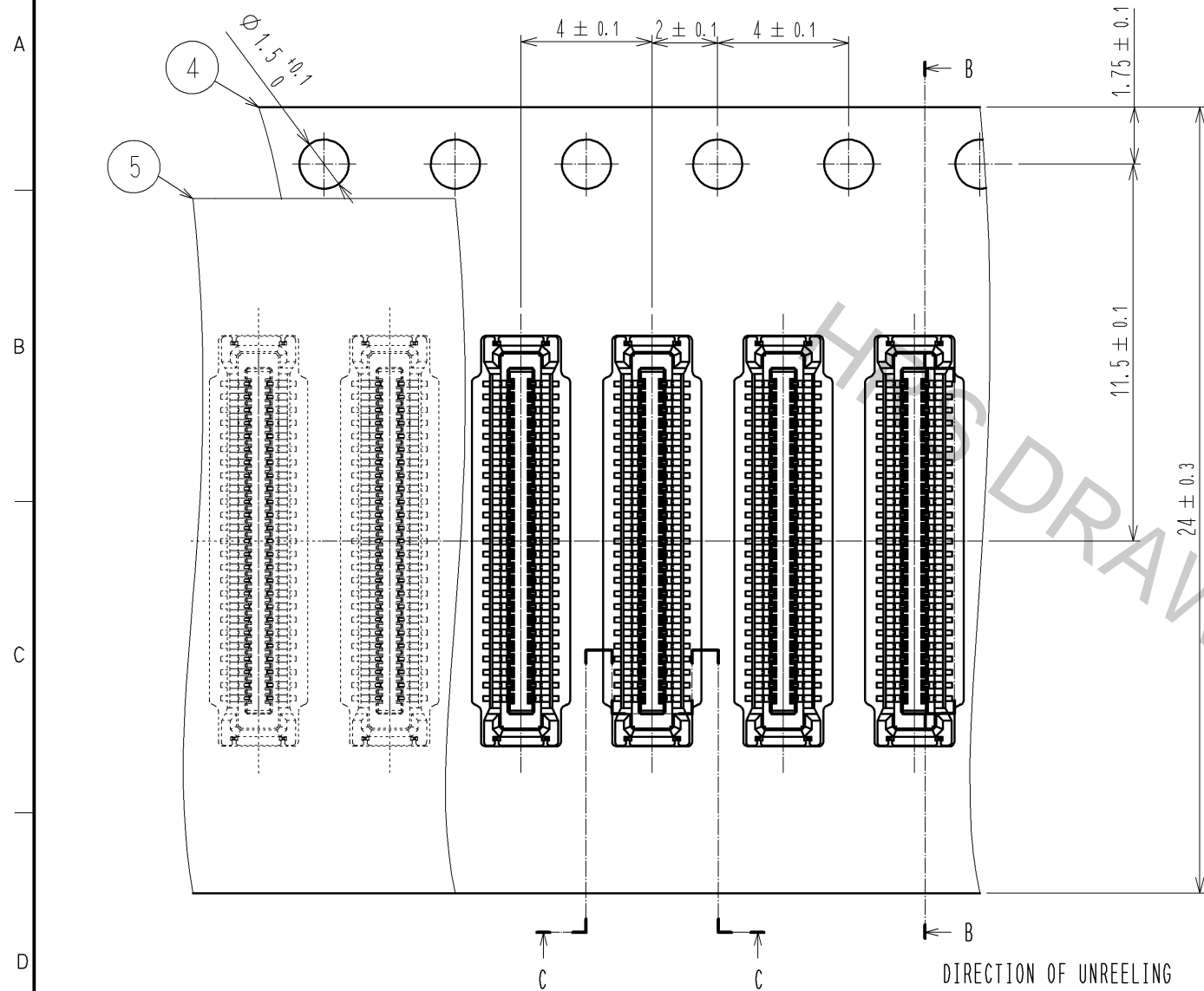


- REFLOW METHOD : IR REFLOW
 NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
- 1) REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC MAX.
 (PEAK TEMPERATURE : 250°C MAX)
 - 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

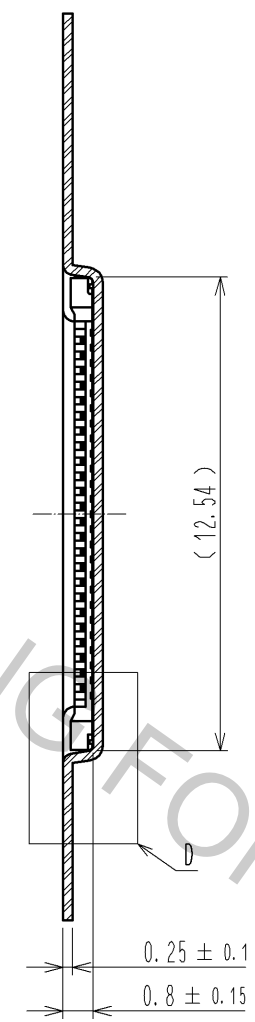
5 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

| | | |
|------------|-------------|--------------------------|
| HRS | DRAWING NO. | EDC3-347101-01 |
| | PART NO. | BM20B(0.6)-50DS-0.4V(51) |
| | CODE NO. | CL684-9314-0-51 |
| | | △ 2/3 |

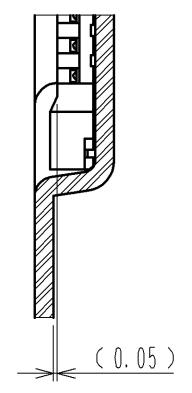
EMBOSSED CARRIER TAPE PACKAGING (5:1)



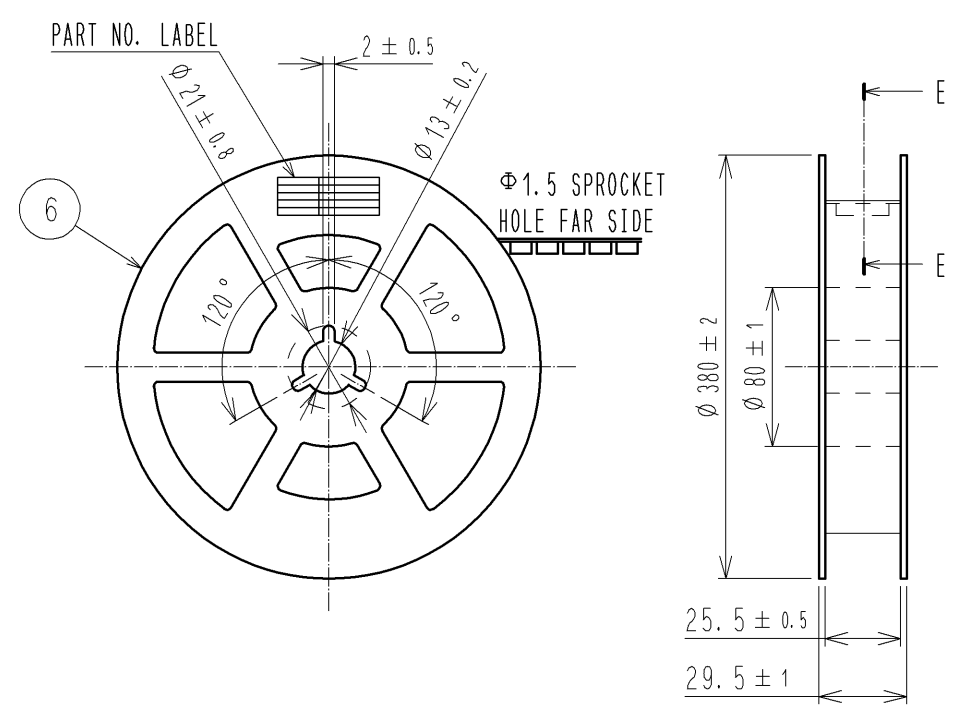
B-B (5:1)



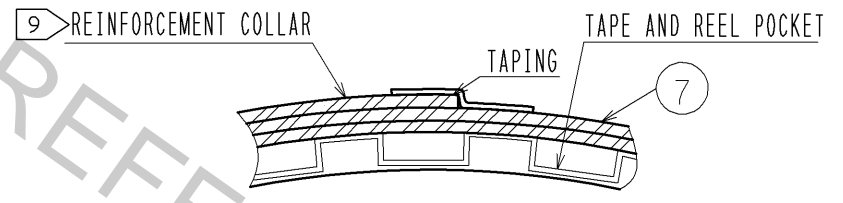
D(10:1)



STYLE AND DIMENTION OF REEL (FREE)



E-E (FREE)



DETAIL OF PART NO. LABEL

| | |
|-------|--------------------------|
| 製造年月日 | ** ** * |
| 製品コード | CL0684-9314-0-51 |
| 製品名 | BM20B(0.6)-50DS-0.4V(51) |
| 数量 | 8,000 |
| 納入者 | ヒロセ電機(株) |

DATA OF MANUFACTURED
CODE NO.
PART NO.
QUANTITY
SUPPLIER

- 6. PER REEL 8000 CONNECTORS.
- 7. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
- 8. REFER TO JIS C 0806 (IEC 60286-3)(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 9. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

| | | |
|------------|-------------|--------------------------|
| HRS | DRAWING NO. | EDC3-347101-01 |
| | PART NO. | BM20B(0.6)-50DS-0.4V(51) |
| | CODE NO. | CL684-9314-0-51 |
| | | \triangle 3/3 |

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